Listing of Claims:

1. (Original): A charge transfer element, comprising:

a reverse conductive type semiconductor region formed in one major surface of one conductive type semiconductor substrate;

a channel region of the one conductive type formed in the semiconductor region so as to extend in one direction;

a plurality of transfer electrodes formed on the semiconductor substrate so as to intersect the channel region;

a capacitance formed continuous from the channel region in the semiconductor region; and

an output transistor having a source and a drain both formed in the semiconductor region, and a gate connected to the capacitance,

wherein

the semiconductor region where the output transistor is formed exhibits an dopant density profile in a depth direction of the semiconductor substrate, which has a maximum dopant density value relative to a middle region of the semiconductor region.

- 2. (Original): The charge transfer element according to claim 1, wherein dopant density of the semiconductor region where the output transistor is formed is lower in a surface region rather than in the middle region along the depth direction of the semiconductor substrate.
- 3. (Original): The charge transfer element according to claim 1, further comprising:

a load transistor serially connected to the output transistor, and

Appl. No. 10/773,112 Amdt. Dated December 7, 2005 Reply to Office Action of September 14, 2005

Attorney Docket No. 81784.0300 Customer No.: 26021

wherein

the load transistor is formed in the semiconductor region where the output transistor is formed.

4. (Original): The charge transfer element according to claim 2, further comprising:

a load transistor serially connected to the output transistor, and wherein

the load transistor is formed in the semiconductor region where the output transistor is formed.